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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	60MHz
Connectivity	I²C, Microwire, SPI, SSI, SSP, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	45
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	40K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 14x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc2146fbd64-557

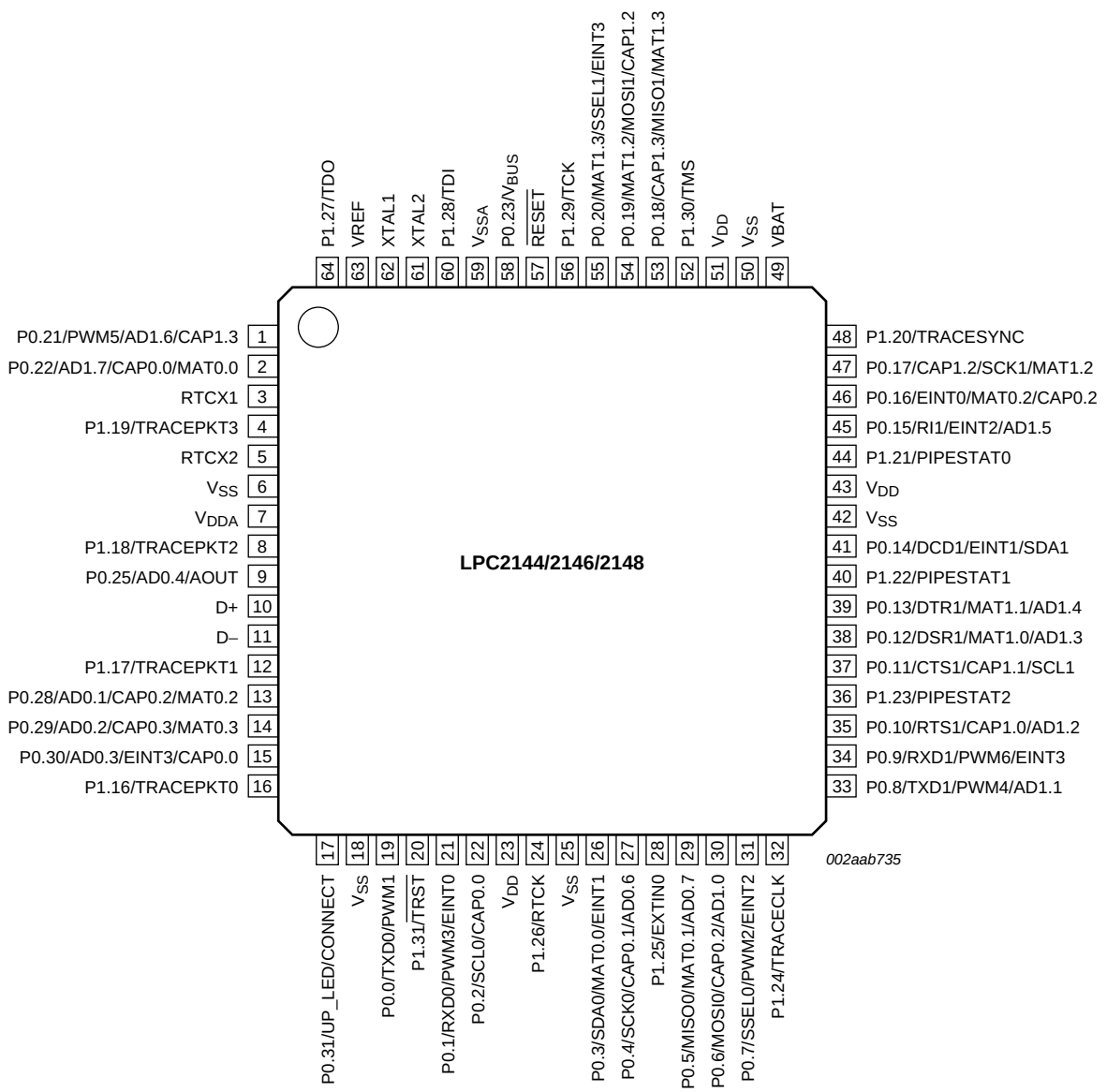


Fig 4. LPC2144/46/48 pinning

5.2 Pin description

Table 3. Pin description

Symbol	Pin	Type	Description
P0.0 to P0.31		I/O	**Port 0:** Port 0 is a 32-bit I/O port with individual direction controls for each bit. Total of 31 pins of the Port 0 can be used as a general purpose bidirectional digital I/Os while P0.31 is output only pin. The operation of port 0 pins depends upon the pin function selected via the pin connect block. Pins P0.24, P0.26 and P0.27 are not available.
P0.0/TXD0/ PWM1	19[1]	I/O	**P0.0 —** General purpose input/output digital pin (GPIO).
		O	**TXD0 —** Transmitter output for UART0.
		O	**PWM1 —** Pulse Width Modulator output 1.
P0.1/RXD0/ PWM3/EINT0	21[2]	I/O	**P0.1 —** General purpose input/output digital pin (GPIO).
		I	**RXD0 —** Receiver input for UART0.
		O	**PWM3 —** Pulse Width Modulator output 3.
		I	**EINT0 —** External interrupt 0 input.
P0.2/SCL0/ CAP0.0	22[3]	I/O	**P0.2 —** General purpose input/output digital pin (GPIO).
		I/O	**SCL0 —** I^2C0 clock input/output. Open-drain output (for I^2C-bus compliance).
		I	**CAP0.0 —** Capture input for Timer 0, channel 0.
P0.3/SDA0/ MAT0.0/EINT1	26[3]	I/O	**P0.3 —** General purpose input/output digital pin (GPIO).
		I/O	**SDA0 —** I^2C0 data input/output. Open-drain output (for I^2C-bus compliance).
		O	**MAT0.0 —** Match output for Timer 0, channel 0.
		I	**EINT1 —** External interrupt 1 input.
P0.4/SCK0/ CAP0.1/AD0.6	27[4]	I/O	**P0.4 —** General purpose input/output digital pin (GPIO).
		I/O	**SCK0 —** Serial clock for SPI0. SPI clock output from master or input to slave.
		I	**CAP0.1 —** Capture input for Timer 0, channel 1.
		I	**AD0.6 —** ADC 0, input 6.
P0.5/MISO0/ MAT0.1/AD0.7	29[4]	I/O	**P0.5 —** General purpose input/output digital pin (GPIO).
		I/O	**MISO0 —** Master In Slave Out for SPI0. Data input to SPI master or data output from SPI slave.
		O	**MAT0.1 —** Match output for Timer 0, channel 1.
		I	**AD0.7 —** ADC 0, input 7.
P0.6/MOSI0/ CAP0.2/AD1.0	30[4]	I/O	**P0.6 —** General purpose input/output digital pin (GPIO).
		I/O	**MOSI0 —** Master Out Slave In for SPI0. Data output from SPI master or data input to SPI slave.
		I	**CAP0.2 —** Capture input for Timer 0, channel 2.
		I	**AD1.0 —** ADC 1, input 0. Available in LPC2144/46/48 only.
P0.7/SSEL0/ PWM2/EINT2	31[2]	I/O	**P0.7 —** General purpose input/output digital pin (GPIO).
		I	**SSEL0 —** Slave Select for SPI0. Selects the SPI interface as a slave.
		O	**PWM2 —** Pulse Width Modulator output 2.
		I	**EINT2 —** External interrupt 2 input.

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
P0.29/AD0.2/ CAP0.3/MAT0.3	14[4]	I/O	**P0.29 —** General purpose input/output digital pin (GPIO).
		I	**AD0.2 —** ADC 0, input 2.
		I	**CAP0.3 —** Capture input for Timer 0, channel 3.
		O	**MAT0.3 —** Match output for Timer 0, channel 3.
P0.30/AD0.3/ EINT3/CAP0.0	15[4]	I/O	**P0.30 —** General purpose input/output digital pin (GPIO).
		I	**AD0.3 —** ADC 0, input 3.
		I	**EINT3 —** External interrupt 3 input.
		I	**CAP0.0 —** Capture input for Timer 0, channel 0.
P0.31/UP_LED/ CONNECT	17[6]	O	**P0.31 —** General purpose output only digital pin (GPO).
		O	**UP_LED —** USB GoodLink LED indicator. It is LOW when device is configured (non-control endpoints enabled). It is HIGH when the device is not configured or during global suspend.
		O	**CONNECT —** Signal used to switch an external 1.5 kΩ resistor under the software control. Used with the SoftConnect USB feature. **Important:** This is an digital output only pin. This pin MUST NOT be externally pulled LOW when RESET pin is LOW or the JTAG port will be disabled.
P1.0 to P1.31		I/O	**Port 1:** Port 1 is a 32-bit bidirectional I/O port with individual direction controls for each bit. The operation of port 1 pins depends upon the pin function selected via the pin connect block. Pins 0 through 15 of port 1 are not available.
P1.16/ TRACEPKT0	16[6]	I/O	**P1.16 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**TRACEPKT0 —** Trace Packet, bit 0.
P1.17/ TRACEPKT1	12[6]	I/O	**P1.17 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**TRACEPKT1 —** Trace Packet, bit 1.
P1.18/ TRACEPKT2	8[6]	I/O	**P1.18 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**TRACEPKT2 —** Trace Packet, bit 2.
P1.19/ TRACEPKT3	4[6]	I/O	**P1.19 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**TRACEPKT3 —** Trace Packet, bit 3.
P1.20/ TRACESYNC	48[6]	I/O	**P1.20 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**TRACESYNC —** Trace Synchronization. **Note:** LOW on this pin while RESET is LOW enables pins P1.25:16 to operate as Trace port after reset.
P1.21/ PIPESTAT0	44[6]	I/O	**P1.21 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**PIPESTAT0 —** Pipeline Status, bit 0.
P1.22/ PIPESTAT1	40[6]	I/O	**P1.22 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**PIPESTAT1 —** Pipeline Status, bit 1.

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
P1.23/ PIPESTAT2	36[6]	I/O	**P1.23 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**PIPESTAT2 —** Pipeline Status, bit 2.
P1.24/ TRACECLK	32[6]	I/O	**P1.24 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		O	**TRACECLK —** Trace Clock.
P1.25/EXTIN0	28[6]	I/O	**P1.25 —** General purpose input/output digital pin (GPIO). Standard I/O port with internal pull-up.
		I	**EXTIN0 —** External Trigger Input.
P1.26/RTCK	24[6]	I/O	**P1.26 —** General purpose input/output digital pin (GPIO).
		I/O	**RTCK —** Returned Test Clock output. Extra signal added to the JTAG port. Assists debugger synchronization when processor frequency varies. Bidirectional pin with internal pull-up. **Note:** LOW on RTCK while $\overline{\text{RESET}}$ is LOW enables pins P1[31:26] to operate as Debug port after reset.
P1.27/TDO	64[6]	I/O	**P1.27 —** General purpose input/output digital pin (GPIO).
		O	**TDO —** Test Data out for JTAG interface.
P1.28/TDI	60[6]	I/O	**P1.28 —** General purpose input/output digital pin (GPIO).
		I	**TDI —** Test Data in for JTAG interface.
P1.29/TCK	56[6]	I/O	**P1.29 —** General purpose input/output digital pin (GPIO).
		I	**TCK —** Test Clock for JTAG interface. This clock must be slower than $^{1}?_{6}$ of the CPU clock (CCLK) for the JTAG interface to operate.
P1.30/TMS	52[6]	I/O	**P1.30 —** General purpose input/output digital pin (GPIO).
		I	**TMS —** Test Mode Select for JTAG interface.
P1.31/$\overline{\text{TRST}}$	20[6]	I/O	**P1.31 —** General purpose input/output digital pin (GPIO).
		I	**$\overline{\text{TRST}}$ —** Test Reset for JTAG interface.
D+	10[7]	I/O	USB bidirectional D+ line.
D−	11[7]	I/O	USB bidirectional D− line.
$\overline{\text{RESET}}$	57[8]	I	**External reset input:** A LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. TTL with hysteresis, 5 V tolerant.
XTAL1	62[9]	I	Input to the oscillator circuit and internal clock generator circuits.
XTAL2	61[9]	O	Output from the oscillator amplifier.
RTCX1	3[9][10]	I	Input to the RTC oscillator circuit.
RTCX2	5[9][10]	O	Output from the RTC oscillator circuit.
V_{SS}	6, 18, 25, 42, 50	I	**Ground:** 0 V reference.
V_{SSA}	59	I	**Analog ground:** 0 V reference. This should nominally be the same voltage as V_{SS}, but should be isolated to minimize noise and error.
V_{DD}	23, 43, 51	I	**3.3 V power supply:** This is the power supply voltage for the core and I/O ports.

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
V_{DDA}	7	I	**Analog 3.3 V power supply:** This should be nominally the same voltage as V_{DD} but should be isolated to minimize noise and error. This voltage is only used to power the on-chip ADC(s) and DAC.
VREF	63	I	**ADC reference voltage:** This should be nominally less than or equal to the V_{DD} voltage but should be isolated to minimize noise and error. Level on this pin is used as a reference for ADC(s) and DAC.
VBAT	49	I	**RTC power supply voltage:** 3.3 V on this pin supplies the power to the RTC.

[1] 5 V tolerant pad (no built-in pull-up resistor) providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control.

[2] 5 V tolerant pad (no built-in pull-up resistor) providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns.

[3] Open-drain 5 V tolerant digital I/O I^2C-bus 400 kHz specification compatible pad. It requires external pull-up to provide an output functionality.

[4] 5 V tolerant pad (no built-in pull-up resistor) providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog input function. If configured for an input function, this pad utilizes built-in glitch filter that blocks pulses shorter than 3 ns. When configured as an ADC input, digital section of the pad is disabled.

[5] 5 V tolerant pad (no built-in pull-up resistor) providing digital I/O (with TTL levels and hysteresis and 10 ns slew rate control) and analog output function. When configured as the DAC output, digital section of the pad is disabled.

[6] 5 V tolerant pad with built-in pull-up resistor providing digital I/O functions with TTL levels and hysteresis and 10 ns slew rate control. The pull-up resistor's value typically ranges from 60 kΩ to 300 kΩ.

[7] Pad is designed in accordance with the Universal Serial Bus (USB) specification, revision 2.0 (Full-speed and Low-speed mode only).

[8] 5 V tolerant pad providing digital input (with TTL levels and hysteresis) function only.

[9] Pad provides special analog functionality.

[10] When unused, the RTCX1 pin can be grounded or left floating. For lowest power leave it floating.
The other RTC pin, RTCX2, should be left floating.

6.3 On-chip static RAM

On-chip static RAM may be used for code and/or data storage. The SRAM may be accessed as 8-bit, 16-bit, and 32-bit. The LPC2141, LPC2142/44 and LPC2146/48 provide 8 kB, 16 kB and 32 kB of static RAM respectively.

In case of LPC2146/48 only, an 8 kB SRAM block intended to be utilized mainly by the USB can also be used as a general purpose RAM for data storage and code storage and execution.

6.4 Memory map

The LPC2141/42/44/46/48 memory map incorporates several distinct regions, as shown in Figure 5.

In addition, the CPU interrupt vectors may be remapped to allow them to reside in either flash memory (the default) or on-chip static RAM. This is described in Section 6.19 “System control”.

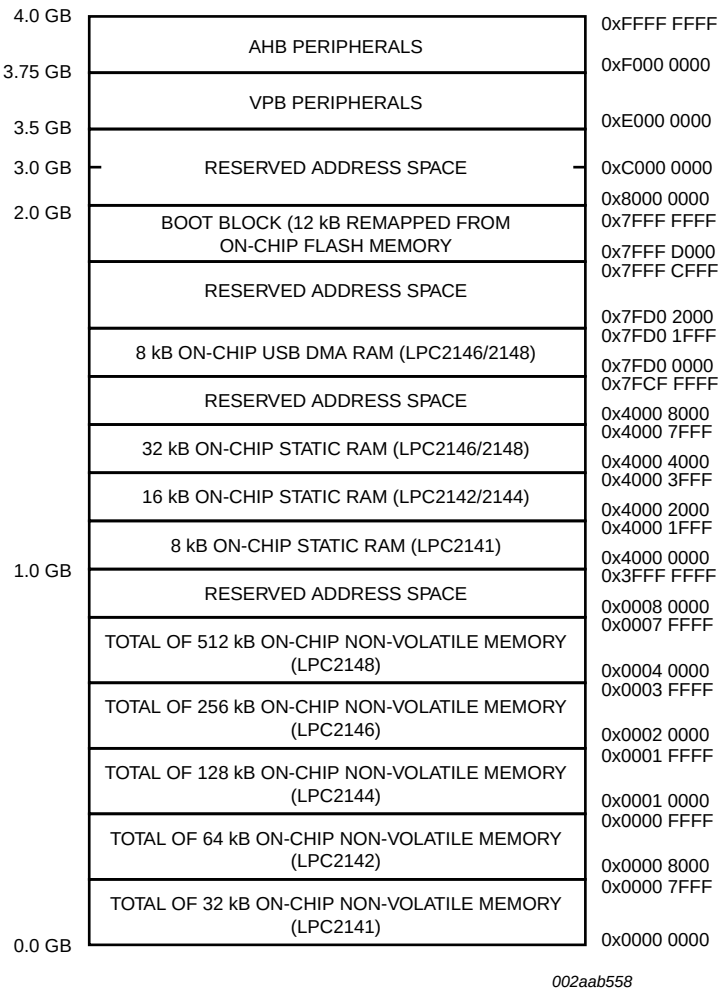


Fig 5. LPC2141/42/44/46/48 memory map

6.7 Fast general purpose parallel I/O (GPIO)

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back, as well as the current state of the port pins.

LPC2141/42/44/46/48 introduce accelerated GPIO functions over prior LPC2000 devices:

- GPIO registers are relocated to the ARM local bus for the fastest possible I/O timing.
- Mask registers allow treating sets of port bits as a group, leaving other bits unchanged.
- All GPIO registers are byte addressable.
- Entire port value can be written in one instruction.

6.7.1 Features

- Bit-level set and clear registers allow a single instruction set or clear of any number of bits in one port.
- Direction control of individual bits.
- Separate control of output set and clear.
- All I/O default to inputs after reset.

6.8 10-bit ADC

The LPC2141/42 contain one and the LPC2144/46/48 contain two analog to digital converters. These converters are single 10-bit successive approximation analog to digital converters. While ADC0 has six channels, ADC1 has eight channels. Therefore, total number of available ADC inputs for LPC2141/42 is 6 and for LPC2144/46/48 is 14.

6.8.1 Features

- 10 bit successive approximation analog to digital converter.
- Measurement range of 0 V to VREF (2.5 V $\leq$ VREF $\leq$ V_{DDA}).
- Each converter capable of performing more than 400000 10-bit samples per second.
- Every analog input has a dedicated result register to reduce interrupt overhead.
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition on input pin or timer match signal.
- Global Start command for both converters (LPC2142/44/46/48 only).

6.9 10-bit DAC

The DAC enables the LPC2141/42/44/46/48 to generate a variable analog output. The maximum DAC output voltage is the VREF voltage.

6.9.1 Features

- 10-bit DAC.
- Buffered output.
- Power-down mode available.

6.11.1 Features

- 16 B Receive and Transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Transmission FIFO control enables implementation of software (XON/XOFF) flow control on both UARTs.
- LPC2144/46/48 UART1 equipped with standard modem interface signals. This module also provides full support for hardware flow control (auto-CTS/RTS).

6.12 I^2C-bus serial I/O controller

The LPC2141/42/44/46/48 each contain two I^2C-bus controllers.

The I^2C-bus is bidirectional, for inter-IC control using only two wires: a Serial Clock Line (SCL), and a Serial DAta line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver or a transmitter with the capability to both receive and send information (such as memory)). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I^2C-bus is a multi-master bus, it can be controlled by more than one bus master connected to it.

The I^2C-bus implemented in LPC2141/42/44/46/48 supports bit rates up to 400 kbit/s (Fast I^2C-bus).

6.12.1 Features

- Compliant with standard I^2C-bus interface.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I^2C-bus can be used for test and diagnostic purposes.

6.13 SPI serial I/O controller

The LPC2141/42/44/46/48 each contain one SPI controller. The SPI is a full duplex serial interface, designed to handle multiple masters and slaves connected to a given bus. Only a single master and a single slave can communicate on the interface during a given data transfer. During a data transfer the master always sends a byte of data to the slave, and the slave always sends a byte of data to the master.

- Match register updates are synchronized with pulse outputs to prevent generation of erroneous pulses. Software must ‘release’ new match values before they can become effective.
- May be used as a standard timer if the PWM mode is not enabled.
- A 32-bit Timer/Counter with a programmable 32-bit Prescaler.

6.19 System control

6.19.1 Crystal oscillator

On-chip integrated oscillator operates with external crystal in range of 1 MHz to 25 MHz. The oscillator output frequency is called f_{osc} and the ARM processor clock frequency is referred to as CCLK for purposes of rate equations, etc. f_{osc} and CCLK are the same value unless the PLL is running and connected. Refer to Section 6.19.2 “PLL” for additional information.

6.19.2 PLL

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up into the range of 10 MHz to 60 MHz with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32 (in practice, the multiplier value cannot be higher than 6 on this family of microcontrollers due to the upper frequency limit of the CPU). The CCO operates in the range of 156 MHz to 320 MHz, so there is an additional divider in the loop to keep the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider may be set to divide by 2, 4, 8, or 16 to produce the output clock. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset and may be enabled by software. The program must configure and activate the PLL, wait for the PLL to Lock, then connect to the PLL as a clock source. The PLL settling time is 100 μs.

6.19.3 Reset and wake-up timer

Reset has two sources on the LPC2141/42/44/46/48: the $\overline{\text{RESET}}$ pin and watchdog reset. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin with an additional glitch filter. Assertion of chip reset by any source starts the Wake-up Timer (see Wake-up Timer description below), causing the internal chip reset to remain asserted until the external reset is de-asserted, the oscillator is running, a fixed number of clocks have passed, and the on-chip flash controller has completed its initialization.

When the internal reset is removed, the processor begins executing at address 0, which is the reset vector. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

The Wake-up Timer ensures that the oscillator and other analog functions required for chip operation are fully functional before the processor is allowed to execute instructions. This is important at power on, all types of reset, and whenever any of the aforementioned functions are turned off for any reason. Since the oscillator and other functions are turned off during Power-down mode, any wake-up of the processor from Power-down mode makes use of the Wake-up Timer.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage (core and external rail)			−0.5	+3.6	V
V_{DDA}	analog 3.3 V pad supply voltage			−0.5	+4.6	V
$V_{i(VBAT)}$	input voltage on pin VBAT	for the RTC		−0.5	+4.6	V
$V_{i(VREF)}$	input voltage on pin VREF			−0.5	+4.6	V
V_{IA}	analog input voltage	on ADC related pins		−0.5	+5.1	V
V_I	input voltage	5 V tolerant I/O pins; only valid when the V_{DD} supply voltage is present	[2]	−0.5	+6.0	V
		other I/O pins	[2][3]	−0.5	V_{DD} + 0.5	V
I_{DD}	supply current	per supply pin	[4]	-	100	mA
I_{SS}	ground current	per ground pin	[4]	-	100	mA
I_{sink}	sink current	for I^2C-bus; DC; T = 85 °C		-	20	mA
T_{stg}	storage temperature		[5]	−65	+150	°C
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W
V_{esd}	electrostatic discharge voltage	human body model	[6]			
		all pins		−4000	+4000	V

[1] The following applies to the Limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Including voltage on outputs in 3-state mode.

[3] Not to exceed 4.6 V.

[4] The peak current is limited to 25 times the corresponding maximum current.

[5] Dependent on package type.

[6] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

Table 5. Static characteristics *…continued*

T_{amb} = −40 °C to +85 °C for commercial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
$I_{DD(act)}$	active mode supply current	V_{DD} = 3.3 V; T_{amb} = 25 °C; code `while(1){}` executed from flash, no active peripherals		-	15	50	
		CCLK = 10 MHz					mA
		CCLK = 60 MHz		-	40	70	mA
		V_{DD} = 3.3 V; T_{amb} = 25 °C; code executed from flash; USB enabled and active; all other peripherals disabled		-	27	70	
		CCLK = 12 MHz					mA
		CCLK = 60 MHz		-	57	90	mA
$I_{DD(pd)}$	Power-down mode supply current	V_{DD} = 3.3 V; T_{amb} = 25 °C		-	40	100	µA
		V_{DD} = 3.3 V; T_{amb} = 85 °C		-	250	500	µA
I_{BATpd}	Power-down mode battery supply current	RTC clock = 32 kHz (from RTCXn pins); T_{amb} = 25 °C	[12]	-	15	30	
		V_{DD} = 3.0 V; $V_{i(VBAT)}$ = 2.5 V					µA
		V_{DD} = 3.0 V; $V_{i(VBAT)}$ = 3.0 V		-	20	40	µA
I_{BATact}	active mode battery supply current	CCLK = 60 MHz; PCLK = 15 MHz; PCLK enabled to RTCK; RTC clock = 32 kHz (from RTCXn pins); T_{amb} = 25 °C	[12]	-	78	-	
		V_{DD} = 3.0 V; $V_{i(VBAT)}$ = 3.0 V					µA
$I_{BATact(opt)}$	optimized active mode battery supply current	PCLK disabled to RTCK in the PCONP register; RTC clock = 32 kHz (from RTCXn pins); T_{amb} = 25 °C; $V_{i(VBAT)}$ = 3.3 V	[12][13]	-	23	-	
		CCLK = 25 MHz					µA
		CCLK = 60 MHz		-	30	-	µA
I^2C-bus pins							
V_{IH}	HIGH-level input voltage			$0.7V_{DD}$	-	-	V
V_{IL}	LOW-level input voltage			-	-	$0.3V_{DD}$	V
V_{hys}	hysteresis voltage			-	$0.05V_{DD}$	-	V
V_{OL}	LOW-level output voltage	I_{OLS} = 3 mA	[8]	-	-	0.4	V
I_{LI}	input leakage current	$V_I = V_{DD}$	[14]	-	2	4	µA
		V_I = 5 V		-	10	22	µA
Oscillator pins							
$V_{i(XTAL1)}$	input voltage on pin XTAL1			−0.5	1.8	1.95	V

Table 5. Static characteristics *…continued*

T_{amb} = −40 °C to +85 °C for commercial applications, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$V_{o(XTAL2)}$	output voltage on pin XTAL2		−0.5	1.8	1.95	V
$V_{i(RTCX1)}$	input voltage on pin RTCX1		−0.5	1.8	1.95	V
$V_{o(RTCX2)}$	output voltage on pin RTCX2		−0.5	1.8	1.95	V
USB pins						
I_{OZ}	OFF-state output current	0 V < V_I < 3.3 V	-	-	±10	μA
V_{BUS}	V_{BUS} line input voltage on the USB connector		-	-	5.25	V
V_{DI}	differential input sensitivity	|(D+) − (D−)|	0.2	-	-	V
V_{CM}	differential common-mode range	includes V_{DI} range	0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage		0.8	-	2.0	V
V_{OL}	LOW output level	R_L of 1.5 kΩ to 3.6 V	-	-	0.3	V
V_{OH}	HIGH output level	R_L of 15 kΩ to GND	2.8	-	3.6	V
C_{trans}	transceiver capacitance	pin to GND	-	-	20	pF
Z_{DRV}	driver output impedance for driver which is not high-speed capable	steady state drive [15]	29	-	44	Ω
R_{pu}	pull-up resistance	SoftConnect = ON	1.1	-	1.9	kΩ

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] Core and external rail.

[3] The RTC typically fails when $V_{i(VBAT)}$ drops below 1.6 V.

[4] Including voltage on outputs in 3-state mode.

[5] V_{DD} supply voltages must be present.

[6] 3-state outputs go into 3-state mode when V_{DD} is grounded.

[7] Please also see the errata note mentioned in errata sheet.

[8] Accounts for 100 mV voltage drop in all supply lines.

[9] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[10] Minimum condition for V_I = 4.5 V, maximum condition for V_I = 5.5 V.

[11] Applies to P1.16 to P1.31.

[12] On pin VBAT.

[13] Optimized for low battery consumption.

[14] To V_{SS}.

[15] Includes external resistors of 33 Ω ± 1 % on D+ and D−.

10. ADC electrical characteristics

Table 8. ADC static characteristics

V_{DDA} = 2.5 V to 3.6 V; T_{amb} = −40 °C to +85 °C unless otherwise specified; ADC frequency 4.5 MHz.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	V_{DDA}	V
C_{ia}	analog input capacitance			-	-	1	pF
E_D	differential linearity error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[1][2]	-	-	±1	LSB
$E_{L(adj)}$	integral non-linearity	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[3]	-	-	±2	LSB
E_O	offset error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[4]	-	-	±3	LSB
E_G	gain error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[5]	-	-	±0.5	%
E_T	absolute error	V_{SSA} = 0 V, V_{DDA} = 3.3 V	[6]	-	-	±4	LSB
R_{vsi}	voltage source interface resistance		[7]	-	-	40	kΩ

[1] The ADC is monotonic, there are no missing codes.

[2] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 8.

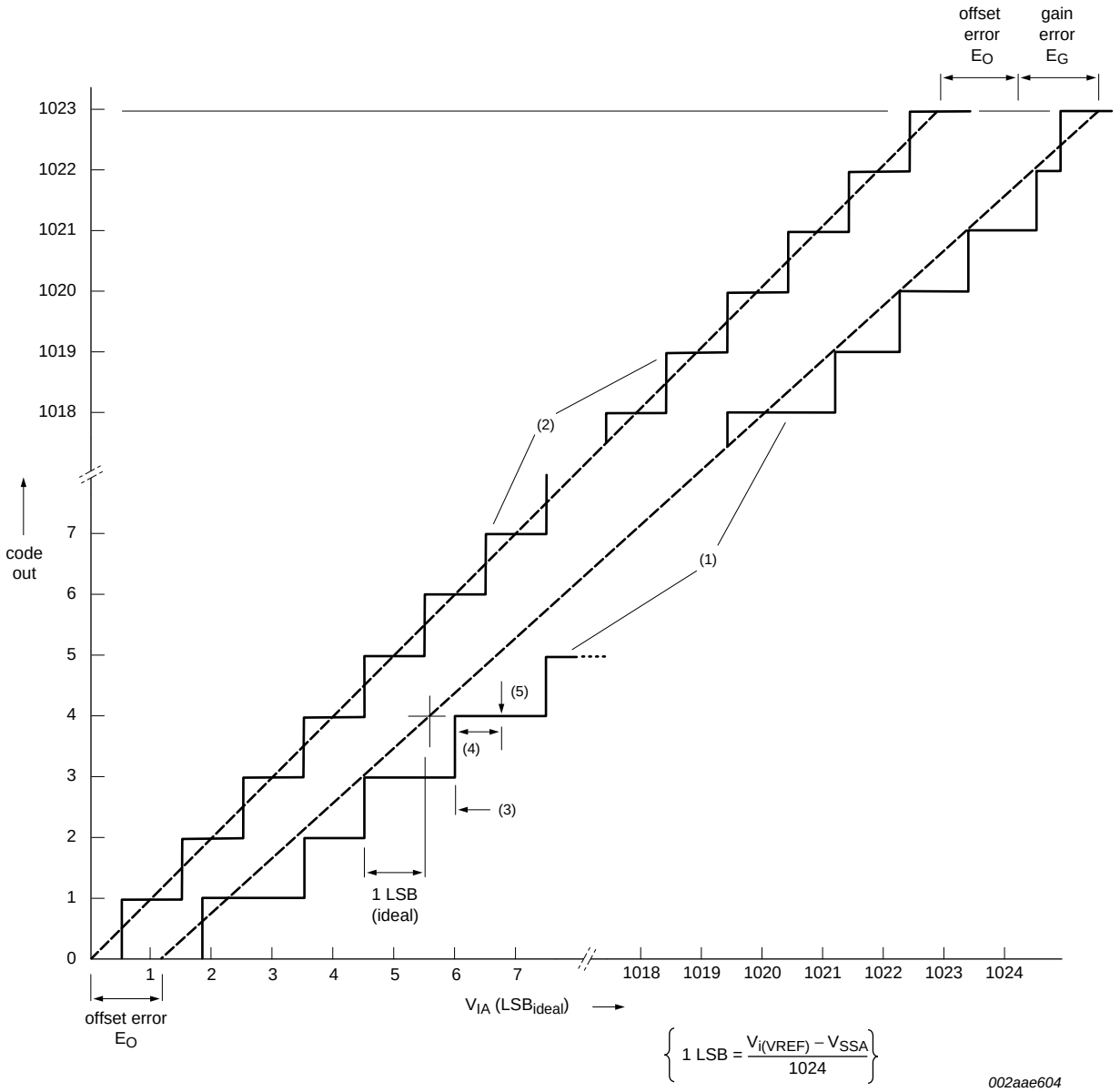
[3] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 8.

[4] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 8.

[5] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 8.

[6] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 8.

[7] See Figure 9.



(1) Example of an actual transfer curve.

(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 8. ADC characteristics

12. Application information

12.1 Suggested USB interface solutions

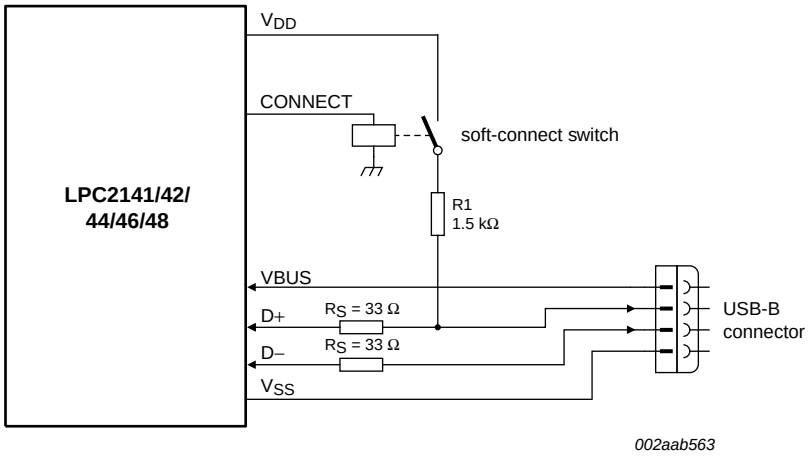


Fig 10. LPC2141/42/44/46/48 USB interface using the CONNECT function on pin 17

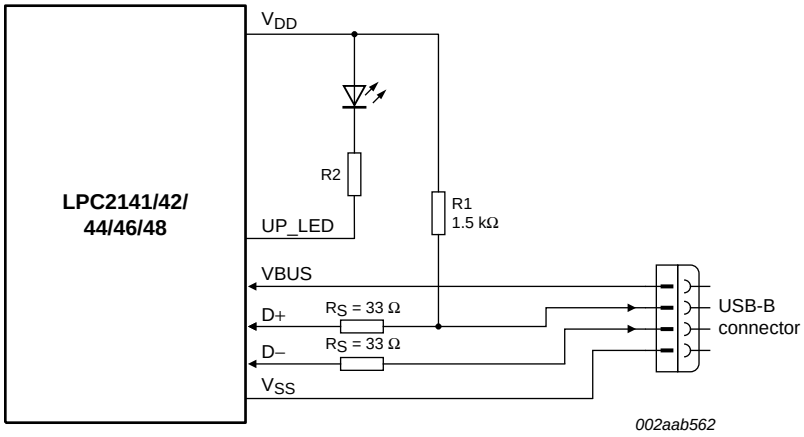


Fig 11. LPC2141/42/44/46/48 USB interface using the UP_LED function on pin 17

12.2 Crystal oscillator XTAL input and component selection

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with C_i = 100 pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor C_i / (C_i + C_g). In slave mode, a minimum of 200 mV (RMS) is needed.

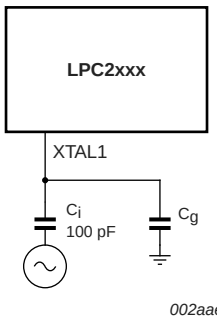


Fig 12. Slave mode operation of the on-chip oscillator

In slave mode the input clock signal should be coupled by means of a capacitor of 100 pF (Figure 12), with an amplitude between 200 mV (RMS) and 1000 mV (RMS). This corresponds to a square wave signal with a signal swing of between 280 mV and 1.4 V. The XTAL2 pin in this configuration can be left unconnected.

External components and models used in oscillation mode are shown in Figure 13 and in Table 10 and Table 11. Since the feedback resistance is integrated on chip, only a crystal and the capacitances C_{X1} and C_{X2} need to be connected externally in case of fundamental mode oscillation (the fundamental frequency is represented by L, C_L and R_S). Capacitance C_P in Figure 13 represents the parallel package capacitance and should not be larger than 7 pF. Parameters F_{OSC}, C_L, R_S and C_P are supplied by the crystal manufacturer.

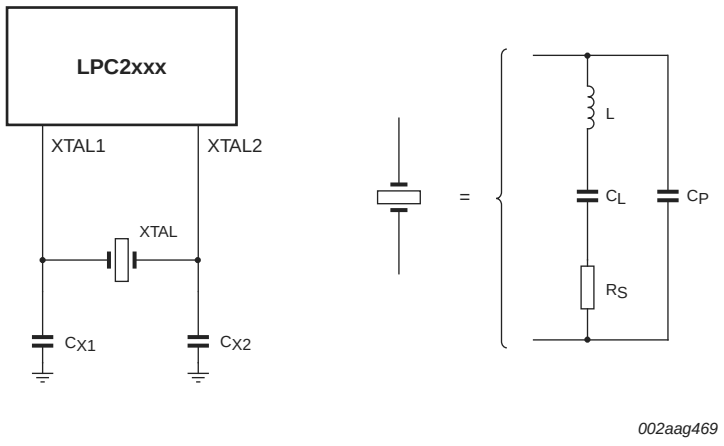


Fig 13. Oscillator modes and models: oscillation mode of operation and external crystal model used for C_{X1}/C_{X2} evaluation

Table 10. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters): low frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}/C_{X2}
1 MHz to 5 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 300 Ω	39 pF, 39 pF
	30 pF	< 300 Ω	57 pF, 57 pF

14. Abbreviations

Table 13. Acronym list

Acronym	Description
ADC	Analog-to-Digital Converter
APB	Advanced Peripheral Bus
BOD	Brown-Out Detection
CPU	Central Processing Unit
DAC	Digital-to-Analog Converter
DCC	Debug Communications Channel
DMA	Direct Memory Access
EOP	End Of Packet
FIFO	First In, First Out
GPIO	General Purpose Input/Output
PLL	Phase-Locked Loop
POR	Power-On Reset
PWM	Pulse Width Modulator
RAM	Random Access Memory
SE0	Single Ended Zero
SPI	Serial Peripheral Interface
SRAM	Static Random Access Memory
SSP	Synchronous Serial Port
UART	Universal Asynchronous Receiver/Transmitter
USB	Universal Serial Bus

16. Legal information

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 12 August 2011
Document identifier: LPC2141_42_44_46_48